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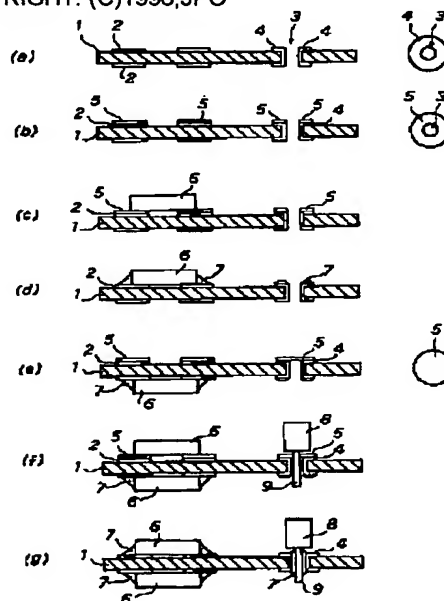
H05K 3/34(21) Application number: **06180076**(71) Applicant: **HITACHI CABLE LTD**(22) Date of filing: **01.08.94**(72) Inventor: **TANAKA HIDEO****(54) MOUNTING OF COMPONENT ON MIXED MOUNTING BOARD****(57) Abstract:**

PURPOSE: To dispense with a hand work process by a method wherein a land on one surface of a board is covered with a solder paste excluding the center part of the land, a land on the opposite surface to the one surface is covered with the paste including the center part of the land and a component is inserted and heated in a through hole to solder it to the board.

CONSTITUTION: A solder paste 5 is printed in such a way as to cover pads 2 on one surface of a and at the same time, the paste 5 is printed on a land 4 excluding the center part of the land 4 and after a surface mounting component 6 is placed on the pads 2, the component 6 is reflow-soldered to the pads 2. Then, this substrate is inverted to print the paste 5 in such a way as to cover pads 2 and at the same time, the paste 5 is printed in such a way as to cover the whole surface of a land 4, a surface mounting component 6 is placed on the pads 2 and an insertion component 8 is inserted in a through hole 3 to reflow-solder to the substrate. Thereby, a soldering of the component 8 is automated and at the same time, the number of processes is

reduced.

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